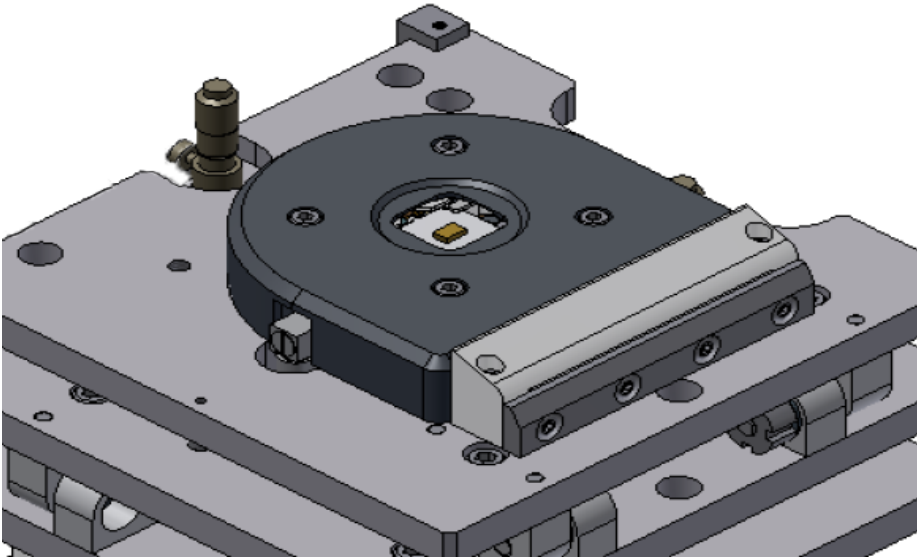
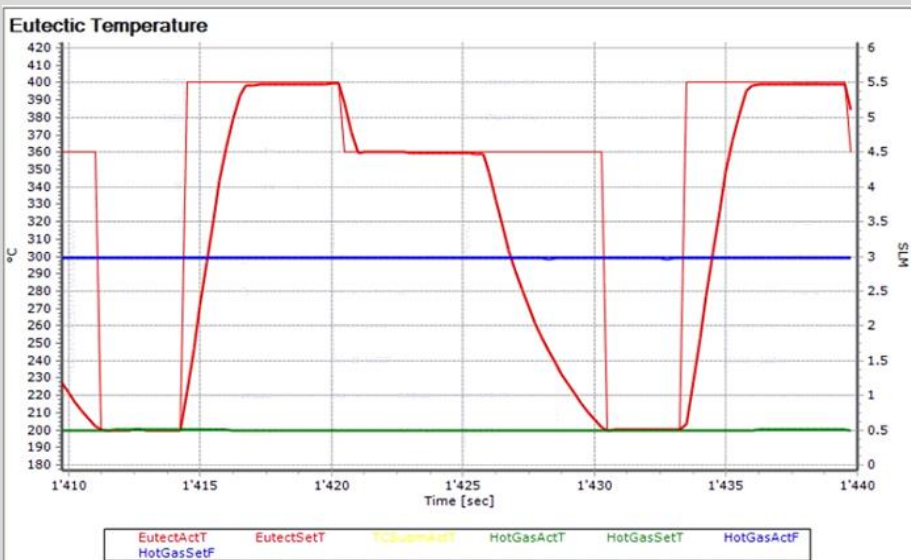


# EUTECTIC BONDING STATION



The Infotech Eutectic Bonding Station features a ceramic heater with fast ramping and cooling rates for die-attach processes. The integrated hot gas heater allows the customer to prevent oxidation with the use of laminar flow forming gas or nitrogen. Additionally, precision tilt micrometers allow for the bonding surface to be aligned to the bond tool to ensure good quality bonds. The flexibility of Infotech systems allows the Eutectic Bonding Station to be combined with other stations and peripherals.

## Process Control Capabilities:



- Real-time heater & hot gas heater temperature feedback
- Oxidation Control w/Real-time hotgas flow monitoring
- Force Feedback & Placement Control
- Possibility to add additional thermocouple for monitoring or process setup
- Vision Inspection to ensure Melted Solder Pre-bond
- Full Traceability & Logging

## General Specifications:

### Heating Plate

- 96VDC - 3.8A @ Room Temperature (25°C)
- Power: 368W at 25°C, 175W at 400°C
- Temperature Feedback via 2 Internal Resistance Temperature Detectors (RTD's)
- Max temperature: 400°C
- Max heating rate: 50°C/s
- Cooling: (cold air/forming gas support)

### Hot Gas Heater

- Voltage: 230 V
- Power: 500 W

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